CRMQGL0303A

N-Channel 30V, 4.1mΩ Typ. Power MOSFET

Description

Features

• 30V, 50A

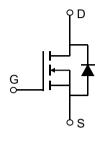
$$R_{DS(ON)}$$
 Typ = 4.1m Ω @ V_{GS} = 10 V

$$R_{DS(ON)}$$
 Typ = 6.3m Ω @ V_{GS} = 4.5V

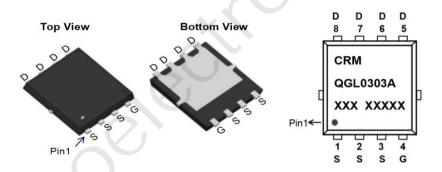
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔVds TESTED!

Application

- Load Switch
- PWM Application
- Power Management







Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQGL0303A	CRMQGL0303A	PDFN3.3x3.3-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		30	V
V _{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	50	Α
I _D	Continuous Drain Current	T _C = 100°C	30	А
I _{DM}	Pulsed Drain Current (1)		200	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		36	mJ
P_{D}	Power Dissipation	T _C = 25°C	24	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		5.2	°C/W
T_{J} , T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C



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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1.0	μΑ
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	1.9	2.4	V
Б		$V_{GS} = 10V, I_D = 12A$	-	4.1	5.3	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 4.5V, I_D = 8A$	-	6.3	8.2	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-(920	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 15V,$ f = 1MHz	X - \	793	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 11VII 12	-	47	-	pF
Q_g	Total Gate Charge		J -	16	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 15V, I_D = 20A$	-	3	-	nC
Q_gd	Gate Drain("Miller") Charge	V _{DS} = 10 V, 1 _D = 20/1	-	3.3	-	nC
Switchin	g Characteristics					
$t_{d(on)}$	Turn-On DelayTime	.r ()	-	6.3	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 15V$	-	3.2	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 20A$, $R_{GEN} = 3\Omega$	-	18	-	ns
t _f	Turn-Off Fall Time	>		3.6		ns
Drain-So	urce Diode Characteristics and N	lax Ratings				
I _S	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	50	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	200	А
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 8A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 - 151 di/d+ - 1001/:	-	27	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 15A$, di/dt = 100A/us	-	11	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =15V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =12A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

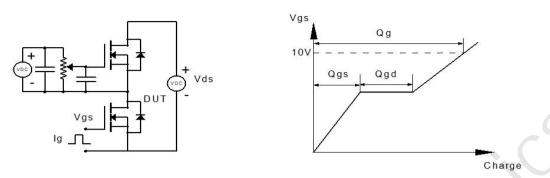


Figure 1: Gate Charge Test Circuit & Waveform

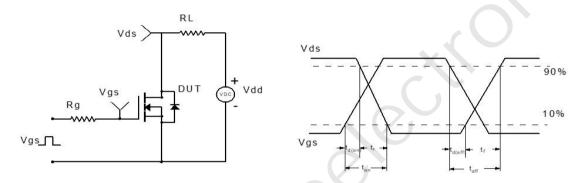


Figure 2: Resistive Switching Test Circuit & Waveform

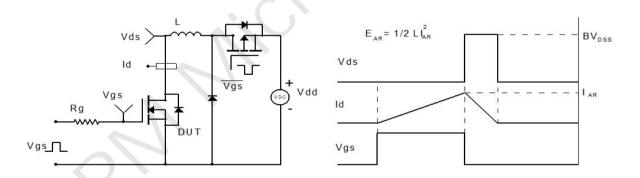


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

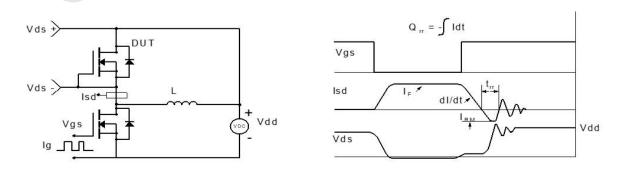
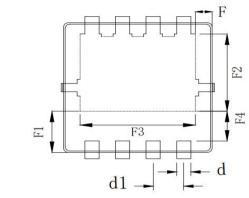


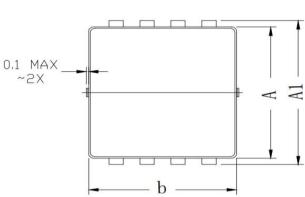
Figure 4: Diode Recovery Test Circuit & Waveform

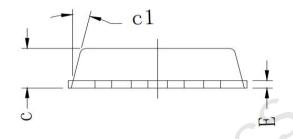
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Package Mechanical Data(PDFN3.3x3.3-8L)







	COMMON DIMI	ENSION (MM)		
PKG	PDFN 3.3×3.3-8L			
SYMBOL	MIN	TYP	MAX	
А	3. 070	3.100	3.130	
A1	3. 300	3.400	3.500	
b	3. 070	3.100	3.130	
С	0. 770	0.800	0. 830	
c1		13°	82	
d	0. 275	0.300	0. 325	
d1	0. 625	0.650	0. 675	
Е	0. 144	0. 152	0. 160	
F	0. 300	0.325	0.350	
F1	0. 960	0.985	1. 010	
F2	1. 775	1.800	1.825	
F3	2. 425	2.450	2. 475	
F4	0.660	0. 685	0.710	

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Contact information

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